SPECIFICATION

COMMERCIALLY AVAILABLE

ITEM: SAW BAND PASS

PART NUMBER: SF-0390008

RoHS

ISSUED / REVISION	ENGINEER APPROVED	DOCUMENT CHECKED	DRAFTSMAN
5/02/18^{kr}			

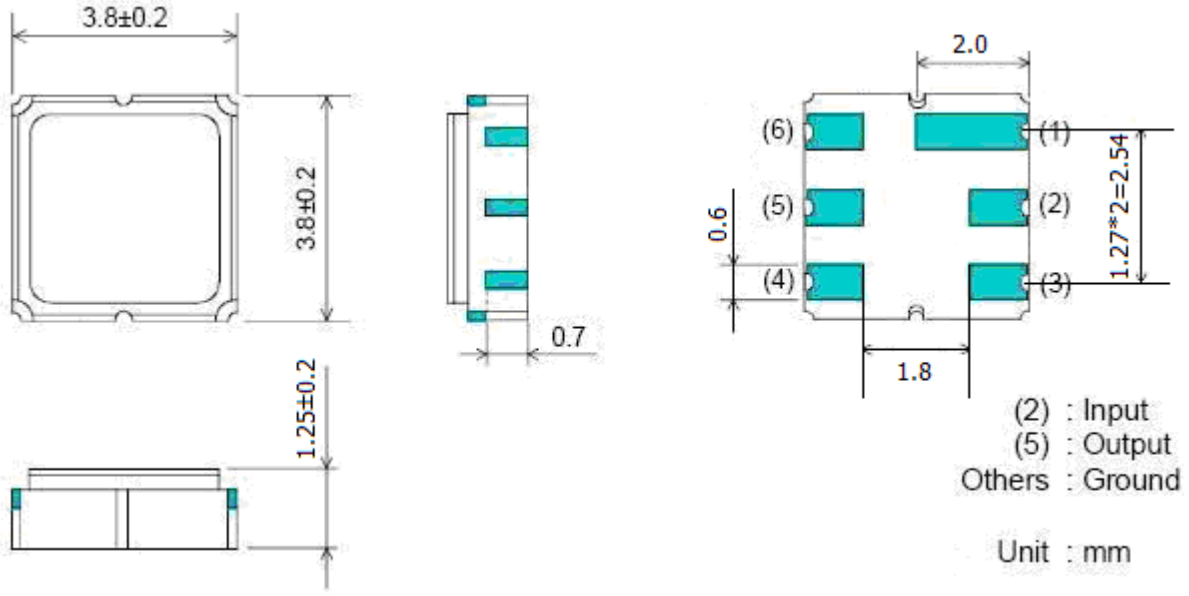
***FILTRO**NETICS Inc*

6010 Parretta Dr. Kansas City, MO 64120
(p) 816-231-7375 (f) 816-241-0368
***FILTRO**NETICS, Inc*
www.filtro.net

1. Electrical Specifications:

		UNIT	MINIMUM	TYPICAL	MAXIMUM
Center Frequency		MHz	-	390	-
Insertion Loss (Fo ± 4 MHz)		dB	-	3	5
Amplitude Ripple (Fo ± 4 MHz)		dB	-	0.6	1
Stop Band Attenuation	At 378 MHz	dB	45	50	-
	At 402 MHz		45	50	-
Group Delay Variation (Fo ± 4 MHz)		ns	-	100	200
Input/Output Impedance		Ω	50		
Maximum Input Power		dBm	+27		
Operating Temperature		°C	-40 ~ +85		
Storage Temperature		°C	-55 ~ +125		

2. Dimension:

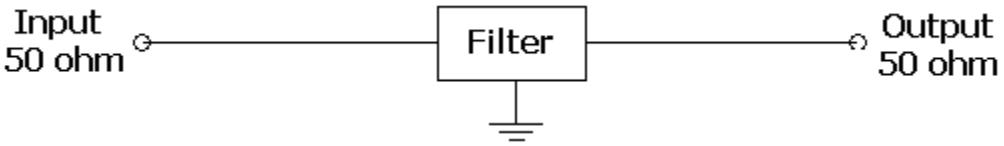


Marking:
Too small for marking

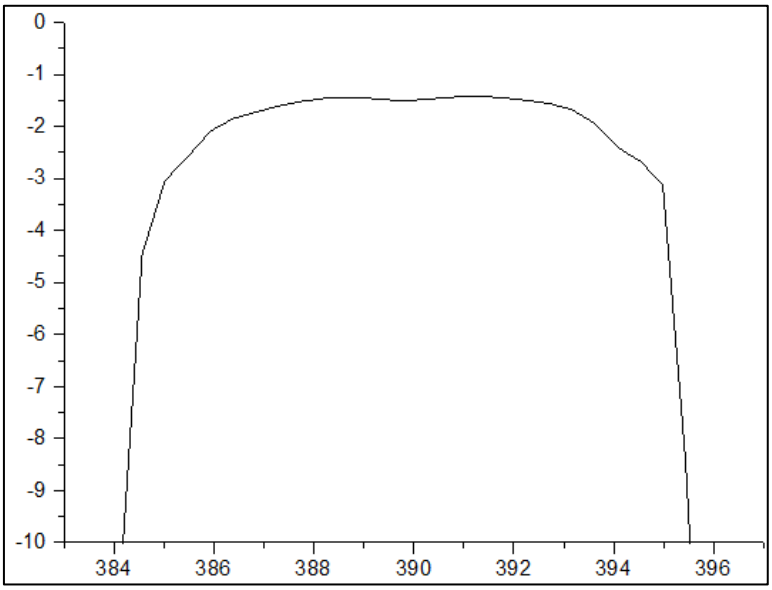
Cautions:

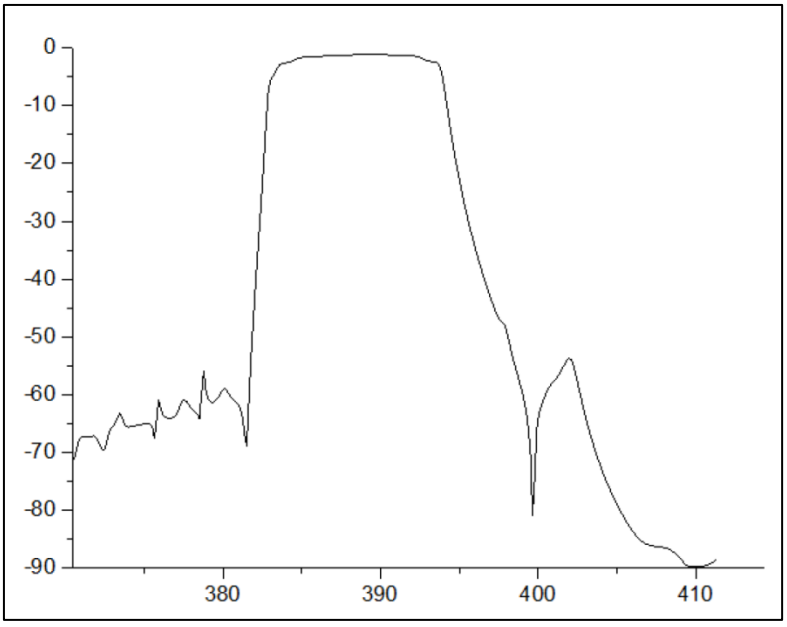
1. **Static Voltage:**
   Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.
2. **Ultrasonic Cleaning:**
   Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.
3. **Soldering:**
   Only leads of component may be soldered. Please avoid soldering another part of component.

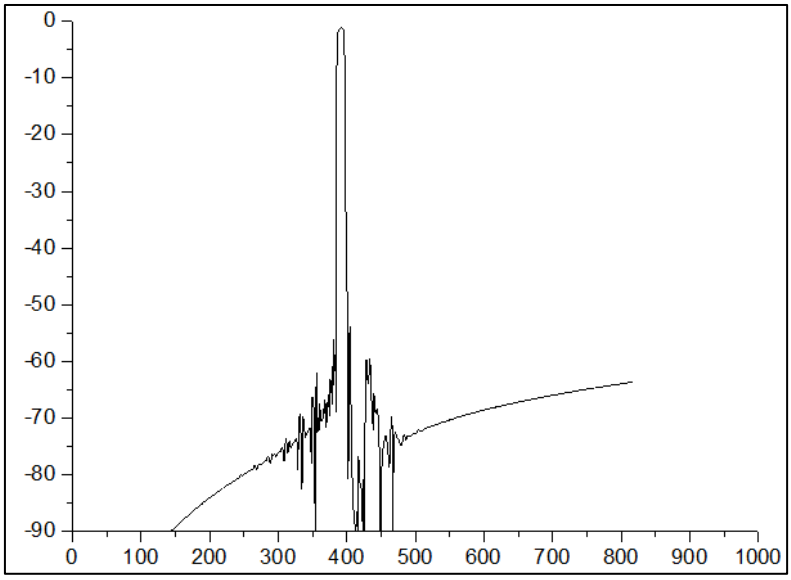
3. Test Circuit



4. Theoretical Response







Environmental Characteristics	
High Temperature Exposure	**Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications.**
Low Temperature Exposure	**Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications.**
Temperature Cycling	**Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 minutes. Then release the device into the room conditions for 24 hours prior to the measurement. The device shall meet the specifications.**
Resistance to solder heat	**Dip the device terminal no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications.**
Solderability	**Subject the device terminals into the solder bath at 245°C ±5°C for 5s. More than 95% area of the terminals must be covered with new solder. It shall meet the specifications.**
Mechanical Shock	**Drop the device randomly onto the concrete floor from the height of 1 m 3 times. The device shall fulfill the specifications.**
Vibration	**Subject the device to the vibration for 1 hour each in x , y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications.**